
Current production quality improves

REPORT OF THE PAC TECH QUALITY MANAGEMENT

- 4 wafers completely bumped (1 at DESY - 3 in Pac Tech stock)
- Quality is comparatively good: (pre bump plasma cleaning step applied)
 - Failure rate per sensor < 1‰
 - Main failure mode:
 - Makro Bump
 - Pad defects
- Bumping test with Senju solderballs running (1 sensor)
- Bonding tests in April:
 - Finetech (2. – 4. April) and
 - Pac Tech (12. – 13. April)
- VTT order data from KIT expected for today

CiS visit is planned for April

Thursday, 19th of April

Attendees so far:

- Jan Hampe
- Doris Eckstein

Who wants to join?